

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Name CGrid RA Bkwy HPro Hdr Tin 6Ckt

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
CGrid RA Bkwy HPro Hdr Tin 6Ckt	Assembly		100	0.528176
COMPONENT CGrid Bkwy Housing	Component		18.7771	0.099176
PBT GF BLACK	Material		18.7771	0.099176
PBT	Substance		11.9547	0.063142
GF-Fibre	Substance		3.3173	0.017521
Flame Retardant, ISO 1043-4 FR(17)	Substance		2.3784	0.012562
Antimonytrioxide	Substance	1309-64-4	0.6259	0.003306
Pigment portion, not to declare	Substance	system	0.2504	0.001322
Further Additives, not to declare	Substance	system	0.2504	0.001322
CGrid Bando Sq Pin WST Tin	Assembly		36.3515	0.192
CGrid Bando Sq Pin WST Unplated	Component		31.2396	0.165
Cartridge Brass 70% Unplated	Material		31.2396	0.165
Copper	Substance	7440-50-8	21.8677	0.1155

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Zinc (metal)	Substance	7440-66-6	9.3719	0.0495
Nickel Plating	Material		1.5336	0.0081
Nickel	Substance	7440-02-0	1.5334	0.008099
Further Additives, not to declare	Substance	system	0.0002	8E-07
Tin Plating	Material		3.5784	0.0189
Tin	Substance	7440-31-5	3.5784	0.0189
CGrid Bando Sq Pin WST Tin	Assembly		44.8714	0.237
CGrid Bando Sq Pin WST Unplated	Component		41.4635	0.219
Cartridge Brass 70% Unplated	Material		41.4635	0.219
Copper	Substance	7440-50-8	29.0244	0.1533
Zinc (metal)	Substance	7440-66-6	12.439	0.0657
Nickel Plating	Material		1.0224	0.0054
Nickel	Substance	7440-02-0	1.0223	0.005399
Further Additives, not to declare	Substance	system	0.0001	5E-07
Tin Plating	Material		2.3856	0.0126
Tin	Substance	7440-31-5	2.3856	0.0126

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

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REACH-SVHC Declaration Information

Regulatory Revision D(2020)4578-DC (25 June 2020)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
lead		*Note	500	Yes
Antimonytrioxide	PBT GF BLACK	*Note	40,000	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes
glass, oxide, chemicals	PBT GF BLACK	*Note	190,000	Yes

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
	44 Concentration within acceptable GADSL limits
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added	
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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Bromine and its compounds	PBT GF BLACK	900	140,000	Yes
Bromine and Chlorine combined	PBT GF BLACK	1,500	140,000	Yes

China ROHS Declaration Information

Part Number 0010883061 Part Name CGrid RA Bkwy HPro Hdr Tin 6Ckt	(e)						
Part Information			Haz	zardous S	Substance	es	
Components		Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
CGrid RA Bkwy HPro Hdr Tin 6Ckt		0	0	0	0	0	0
COMPONENT CGrid Bkwy Housing		0	0	0	0	0	0
CGrid Bando Sq Pin WST Tin		0	0	0	0	0	0
CGrid Bando Sq Pin WST Unplated		0	0	0	0	0	0
CGrid Bando Sq Pin WST Tin		0	0	0	0	0	0
CGrid Bando Sq Pin WST Unplated		0	0	0	0	0	0

Process Information

Component Plating / Surface Finish	BSn-Ni
Termination Base Alloy	P-Bronze
Solder Alloy	N/A
Process Capability	WAVE
Maximum Exposure Time (seconds)	005
Maximum Process Temperature (C)	235
Maximum Cycles at Reflow Temperature	001
J-STD-020 Moisture Sensitivity Level	N/A

Jan 18, 2021

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